

192 GHz push-push VCO in 0.13 μm CMOS

C. Cao, E. Seok and K.K. O

A 192 GHz cross-coupled push-push voltage controlled oscillator (VCO) is fabricated using the UMC 0.13 μm CMOS logic process. The VCO can be tuned from 191.4 to 192.7 GHz. The VCO provides output power of ~ -20 dBm and phase noise of ~ -100 dBc/Hz at 10 MHz offset, while consuming 11 mA from a 1.5 V supply.

Introduction: With the rapid advance of high frequency capability for CMOS technology, millimetre-wave CMOS VCOs with ~ 100 GHz fundamental operating frequency have been reported [1, 2]. The fundamental oscillation frequency is limited by unity power gain frequency f_{max} of the transistor. To obtain even higher frequencies, push-push VCOs [3–5] using the second harmonic operating at up to 131 GHz have been demonstrated in a 90 nm CMOS technology [5]. In push-push VCOs, besides higher device gain, varactor and capacitor Q factors are higher, while the transmission line loss is lower at a given output frequency since the fundamental frequency of the oscillator is one half of the output frequency. In this Letter we report a 192 GHz push-push VCO fabricated using the 0.13 μm UMC logic process with eight copper layers. Oscillators such as this can be used in remote sensing and advanced imaging applications [6] and suggest that THz CMOS circuits will be available in the near future.

Circuit design: Fig. 1 shows the schematic of the VCO. Cross-coupled transistors M_1 and M_2 form the VCO core. Inductors, L_1 and L_2 (~ 45 pH), accumulation mode MOS capacitors, and the capacitances associated with M_1 and M_2 serve as the LC resonant tank. A key to achieving high fundamental operating frequency is minimising the parasitic capacitances connected to the LC tank [2]. At the virtual ground nodes, the anti-phase fundamental signals cancel out and the second-harmonic signal can be extracted. The middle point of inductors L_1 and L_2 has the lowest parasitic capacitance to ground among the common-mode nodes. This makes the impedance at resonant frequency the highest and the best port to extract the push-push output [3–5]. A quarter wavelength transmission line tuned for the second-harmonic frequency is usually used to increase the amplitude of the second harmonic while suppressing the fundamental signal [3–5]. In this design, the transmission line and the current source transistor are broken into two parts to make the layout symmetric, which better suppresses the fundamental signal at the common-mode nodes.

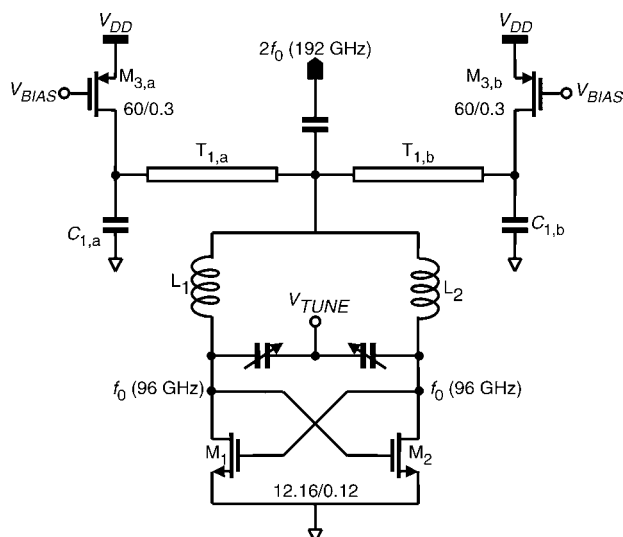


Fig. 1 Schematic of push-push VCO

The transmission line structure is shown in Fig. 2 and is formed using the grounded coplanar waveguide (CPW) structure [7, 8]. Compared to the conventional CPW, the ground plane isolates the line from the lossy silicon substrate and reduces the insertion loss. The lines are formed using the top metal (8) layer and the ground plane is formed by metal 1. The transmission line width and gap are 3 and 4 μm , respectively.

The characteristic impedance of the line is $\sim 65 \Omega$. The length of lines is 150 μm . This length is slightly shorter than $\lambda/4$, so that the impedance looking into the transmission line is inductive to resonate the capacitances from the pad and other metal interconnections. The 2 pF bypass capacitors ($C_{1,a}$, $C_{1,b}$ in Fig. 1) serve as a short around 190 GHz. They are formed using the parasitic capacitance between adjacent metal layers [9]. The metal 8, 6, 4 and 2 layers form the top plate, and metal 7, 5, 3 and 1 layers form the bottom plate. The capacitance density is $0.55 \text{ fF}/\mu\text{m}^2$. The transmission lines and bypass capacitors are simulated using the Ansoft HFSS, a 3D EM simulator. Two VCOs are implemented. In the first version, to achieve higher oscillation frequency, the output buffers and bond pads for the fundamental output were not included. The chip occupies $450 \times 390 \mu\text{m}$ including the bond pads. A micrograph is shown in Fig. 3. The second VCO, including the buffers for both the fundamental and push-push port, was also fabricated. Owing to the capacitance from output buffer, the measured fundamental oscillation frequency is about 4 GHz lower.

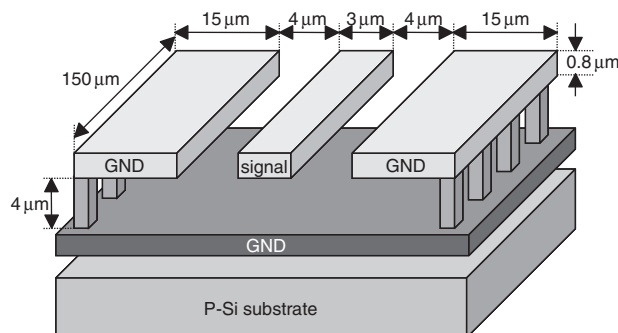


Fig. 2 Grounded coplanar waveguide transmission line

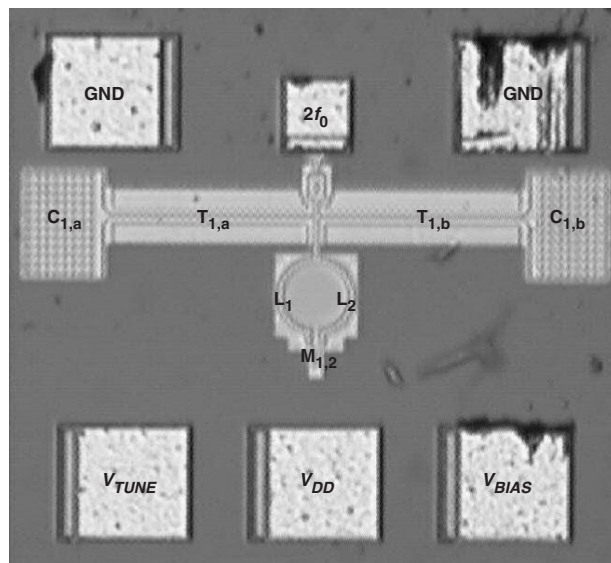


Fig. 3 Micrograph of chip

Experiment results: The chip was measured on-wafer using a GGB WR-5 (140–220 GHz) waveguide probe. The cutoff frequency of the TE₁₀ mode in the WR-5 waveguide is 115.7 GHz, which attenuates the fundamental signal entering the harmonic mixer. The VCO output spectrum is measured using an OML M05HWD (140–220 GHz) harmonic mixer and an Agilent E4448A 50 GHz spectrum analyser. An Agilent 11970W (75–110 GHz) harmonic mixer has also been used to evaluate the fundamental output.

The circuit starts to oscillate with 3.2 mA current. However, no signal was detected at the push-push port until the bias current is increased to above 8 mA owing to the detection limit of the measurement setup. To increase the output level, the circuit is measured with 11 mA bias current from a 1.5 V supply. Fig. 4 shows the output spectrum and the measured signal level is -82 dBm. The conversion loss of the harmonic mixer is ~ 60 dB at 190 GHz. The insertion loss of the probe is about 2 dB. Thus, the signal is estimated to be about -20 dBm. The oscillation frequency can be tuned from 191.4 to 192.7 GHz by

Report Documentation Page				Form Approved OMB No. 0704-0188	
Public reporting burden for the collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington VA 22202-4302. Respondents should be aware that notwithstanding any other provision of law, no person shall be subject to a penalty for failing to comply with a collection of information if it does not display a currently valid OMB control number.					
1. REPORT DATE FEB 2006		2. REPORT TYPE		3. DATES COVERED 00-00-2006 to 00-00-2006	
4. TITLE AND SUBTITLE 192 GHz push-push VCO in 0.13 um CMOS				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) University of Florida, Department of Electrical and Computer Engineering, Gainesville, FL, 32611				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT Approved for public release; distribution unlimited					
13. SUPPLEMENTARY NOTES					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT	18. NUMBER OF PAGES 2	19a. NAME OF RESPONSIBLE PERSON
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified			

changing V_{TUNE} from 0 to 1.8 V. Because the output of harmonic mixer is weak, the phase noise could not be directly measured. The phase noise of the fundamental output is -106 dBc/Hz at 10 MHz offset for the VCO with the output buffer. The phase noise at the push-push port is expected to be 6 dB higher. Owing to the coupling through the substrate and metal interconnection, the fundamental signal also appears at the push-push port. The measured fundamental signal is about -30 to -25 dBm at the push-push port after calibrating the losses. As expected, the frequency range of the fundamental signal is exactly one half of the second harmonic.

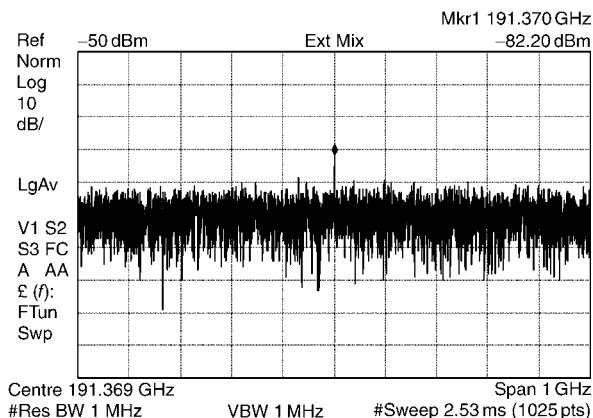


Fig. 4 Measured VCO output spectrum

Conclusions: A 192 GHz push-push VCO fabricated in the UMC 0.13 μ m CMOS process is presented. 192 GHz is the highest operating frequency for any silicon-based circuits. Given that the state of the art is 65 nm, generation of THz signals using CMOS technology cannot be far in the future.

Acknowledgments: This work is supported by DARPA (N66001-03-1-8911). The authors also thank UMC Inc. and Bitwave Semiconductor Inc. for chip fabrication.

© IEE 2006

29 November 2005

Electronics Letters online no: 20064159

doi: 10.1049/el:20064159

C. Cao, E. Seok and K.K. O (Department of Electrical and Computer Engineering, 538 Engineering Building, University of Florida, Gainesville, FL 32611, USA)

E-mail: cao@tec.ufl.edu

References

- 1 Franca-Neto, L.M., Bishop, R.E., and Bloechel, B.A.: '64 GHz and 100 GHz VCO's in 90 nm CMOS using optimum pumping method'. IEEE Int. Solid-State Circuits Conf. Dig. Tech. Pprs, February 2004, pp. 444–445
- 2 Cao, C., and O, K.K.: 'A 90-GHz voltage-controlled oscillator with a 2.2-GHz tuning range in a 130-nm CMOS technology'. Symp. on VLSI Circuits Dig. Tech. Pprs, June 2005, pp. 242–243
- 3 Liu, R.C., Chang, H.-Y., Wang, C.-H., and Wang, H.: 'A 63 GHz VCO using a standard 0.25 μ m CMOS process'. IEEE Int. Solid-State Circuit Conf. Dig. Tech. Pprs, February 2004, pp. 446–447
- 4 Huang, P.-C., Tsai, M.-D., Wang, H., Chen, C.-H., and Chang, C.-S.: 'A 114 GHz VCO in 0.13 μ m CMOS technology'. IEEE Int. Solid-State Circuits Conf. Dig. Tech. Pprs, February 2005, Vol. 237, pp. 404–405
- 5 Huang, P.-C., Liu, R.-C., Chang, H.-Y., Lin, C.-S., Lei, M.-F., Wang, H., Su, C.-Y., and Chang, C.-L.: 'A 131 GHz push-push VCO in 90-nm CMOS technology'. IEEE RFIC Symp. Dig. Pprs, June 2005, pp. 613–616
- 6 Siegel, P.H.: 'Terahertz technology', *IEEE Trans. Microw. Theory Tech.*, 2002, **50**, (3), pp. 910–928
- 7 Robert, A.P.: 'Design consideration for monolithic microwave circuits', *IEEE Trans. Microw. Theory Tech.*, 1981, **29**, (6), pp. 513–535
- 8 Komijani, A., and Hajimiri, A.: 'A 24 GHz, +14.5 dBm fully-integrated power amplifier in 0.18 μ m CMOS'. IEEE CICC Dig. Tech. Pprs, October 2004, pp. 561–564
- 9 Li, Z., and O, K.K.: '15-GHz fully integrated nMOS switches in a 0.13- μ m CMOS process', *IEEE J. Solid-State Circuits*, 2005, **40**, (11), pp. 2323–2328